



Material Content Data Sheet



Sales Product Name		BSC0924NDI		Issued		28. July 2015		
MA#		MA001013784						
Package		PG-TISON-8-2		Weight*		96.44 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.495	0.51	0.51	5132	5132
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		106	
	non noble metal	zinc	7440-66-6	0.041	0.04		426	
	non noble metal	iron	7439-89-6	0.822	0.85		8520	
wire	non noble metal	copper	7440-50-8	33.360	34.59	35.49	345930	354982
	noble metal	gold	7440-57-5	0.062	0.06	0.06	641	641
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.10		993
plastics	plastics	epoxy resin	-	4.933	5.11		51148	
	inorganic material	silicondioxide	60676-86-0	42.860	44.48	49.69	444442	496583
	leadfinish	non noble metal	tin	7440-31-5	1.122	1.16	1.16	11633
plating	noble metal	silver	7440-22-4	0.186	0.19	0.19	1926	1926
solder	noble metal	silver	7440-22-4	0.021	0.02		218	
	non noble metal	tin	7440-31-5	0.017	0.02		175	
	non noble metal	lead	7439-92-1	0.805	0.83	0.87	8344	8737
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.003	0.00		36	
	non noble metal	zinc	7440-66-6	0.014	0.01		144	
	non noble metal	iron	7439-89-6	0.279	0.29		2889	
	non noble metal	copper	7440-50-8	11.312	11.73	12.03	117297	120366
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com